Inventor:

Arup Bhattacharyya

Title:

Semiconductor-On-Insulator Thin Film Transistor Constructions

Assignee:

Micron Technology, Inc.

INFORMATION DISCLOSURE STATEMENT

PURSUANT TO 37 C.F.R. §§1.56, 1.97 AND 1.98

In compliance with 37 C.F.R. §§1.56, 1.97 and 1.98, your attention

is directed to the United States patents and other references listed on the

attached Form PTO-1449.

The listed references were cited by, or submitted to, the Office in

the parent, co-pending application of the above-identified application. The

above-identified application is a divisional of co-pending application Serial

No. 10/243,180 filed September 12, 2002. Such prior disclosure is

sufficient for the above-identified application as far as copies of the

references are concerned. 37 C.F.R. §1.98(d) and MPEP §609(2). No

admission is made regarding whether all the submitted references are prior

art.

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: JULY 22, 2003 Attorney:

David G. Latwesen, Ph.D. Reg. #38,533

WELLS ST. JOHN P.S.

Form PTO-1449	U.S. DEPARTMENT OF COM PATENT AND TRADEMARK		ATTY. DOCKET NO. MI22-2362	PRIORITY SERIAL NO 10/243,180	
	LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)		APPLICANT Arup Bhattacharyya		
	(**************************************		PRIORITY FILING DATE September 12, 2002	PRIORITY GROUP 2818	
	OTHER REFERENCES (including Author	, Title, Dat	e, Pertinent Pages, Etc.)		
AA	Ono, K. et al., "Analysis of Current-Voltage Ch	Ono, K. et al., "Analysis of Current-Voltage Characteristics in Polysilicon TFTs for LCDs", IEDM Tech. Digest,			
	1988, pp. 256-259.				
AB	Yamauchi, N. et al., "Drastically Improved Perf	uchi, N. et al., *Drastically Improved Performance in Poly-Si TFTs with Channel Dimensions Comparable to			
	Grain Size", IEDM Tech. Digest, 1989, pp	Grain Size*, IEDM Tech. Digest, 1989, pp. 353-356.			
AC	King, T. et al, "A Low-Temperature (s550°C) S	King, T. et al, *A Low-Temperature (≤550°C) Silicon-Germanium MOS Thin-Film Transistor Technology for			
	Large-Area Electronics*, IEDM Tech. Dige	Large-Area Electronics*, IEDM Tech. Digest, 1991, pp. 567-570.			
AD	Kuriyama, H. et al., "High Mobility Poly-Si TFT	Kuriyama, H. et al., "High Mobility Poly-Si TFT by a New Excimer Laser Annealing Method for Large Area			
	Electronics*, IEDM Tech. Digest, 1991, pp	Electronics*, IEDM Tech. Digest, 1991, pp. 563-566.			
AE	Jeon, J. et al., "A New Poly-Si TFT with Select	Jeon, J. et al., *A New Poly-Si TFT with Selectively Doped Channel Fabricated by Novel Excimer Laser			
	Annealing*, IEDM Tech. Digest, 2000, pp.	Annealing*, IEDM Tech. Digest, 2000, pp. 213-216.			
AF	Kim, C.H. et al., "A New High -Performance P	Kim, C.H. et al., "A New High -Performance Poly-Si TFT by Simple Excimer Laser Annealing on Selectively			
	Floating a-Si Layer", IEDM Tech. Digest, 2001, pp. 751-754.				
AG	Hara, A. et al, "Selective Single-Crystalline-Silic	Hara, A. et al, "Selective Single-Crystalline-Silicon Growth at the Pre-Defined Active Regions of TFTs on a Glass			
	by a Scanning CW Layer Irradiation", IED	by a Scanning CW Layer Irradiation*, IEDM Tech. Digest, 2000, pp. 209-212.			
АН	Hara, A. et al., "High Performance Poly-Si TFT	Hara, A. et al., "High Performance Poly-Si TFTs on a Glass by a Stable Scanning CW Laser Lateral			
	Crystallization*, IEDM Tech. Digest, 2001,	pp. 747-	750.		
AI	Jagar, S. et al., "Single Grain Thin-Fim-Transistor (TFT) with SOI CMOS Performance Formed by				
	Metal-Induced-Lateral-Crystallization*, IEDN	Metal-Induced-Lateral-Crystallization*, IEDM Tech. Digest, 1999, p. 293-296.			
LA L	Gu, J. et al., "High Performance Sub-100 nm	Si Thin-F	Im Transistors by Pattern-Contro	lled Crystallization of Thin	
	Channel Layer and High Temperature And	Channel Layer and High Temperature Annealing*, DRC Conference Digest, 2002, pp. 49-50.			
AK	Kesan, V. et al., "High Performance 0.25μm p-MOSFETs with Silicon- Germanium Channels for 300K and 77K				
Ī	Operation*, IEDM Tech. Digest, 1991, pp. 25-28.				
AL	Garone, P.M. et al., *Mobility Enhancement and	d Quantu	n Mechanical Modeling in Ge _x Si	1-x Channel MOSFETs from	
	90 to 300K*, IEDM Tech. Digest, 1991, p	90 to 300K*, IEDM Tech. Digest, 1991, pp. 29-32.			
EXAMINER	DATE	CONSID	ERED		
	tial if reference considered, whether or not citation is in ot considered. Include copy of this form with next comm			hrough citation if not in	

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE ST OF ART CITED BY APPLICANT (Use several sheets if necessary)	ATTY. DOCKET NO. MI22-2362	PRIORITY SERIAL NO 10/243,180		
			APPLICANT Arup Bhattacharyya			
			PRIORITY FILING DATE September 12, 2002	PRIORITY GROUP 2818		
		OTHER REFERENCES (including Author, Title, D	ate, Pertinent Pages, Etc.)			
АМ		Feder, B.J., "I.B.M. Finds Way to Speed Up Chips", The New York Times, June 8, 2001, reprinted from				
		http://www.nytimes.com/2001/06/08 /technology/08BLUE.html, 2 pgs.				
AN		Rim, K. et al., "Strained Si NMOSFET's for High Performance CMOS Technology", 2001 Sympos. on VLSI Tech.				
		Digest of Technical Papers, p. 59-60.				
AO		Li, P. et al., *Design of High Speed Si/SiGe Heterojunction Complementary MOSFETs with Reduced Short-Channel				
		Effects*, Natl. Central University, ChungLi, Taiwan, National Science Council of Taiwan., pp. 1, 9.	ROC, Aug. 2001, Contract No.	NSC 89-2215-E-008-049		
AP		Ernst, T. et al., "Fabrication of a Novel Strained SiGe:C-channel Planar 55 nm nMOSFET for High-Performance				
		CMOS*, 2002 Sympos. on VLSt Tech. Digest of Technical Papers, pp. 92-93.				
AQ		Rim, K. et al., "Characteristics and Device Design of Sub-100 nm Strained SiN- and PMOSFETs", 2002 Sympos.				
		on VLSI Tech. Digest of Technical Papers, pp. 98-99.				
AR		Belford, R.E. et al., "Performance-Augmented CMOS Using Back-End Uniaxial Strain", DRC Conf. Digest, 2002,				
		pp. 41-42.				
AS		Shima, M. et al., "<100> Channel Strained-SiGe p-MOSFET with Enhanced Hole Mobility and Lower Parasitic				
		Resistance*, 2002 Sympos. on VLSI Tech. Digest of Technical Papers, pp. 94-95.				
AT		Nayfeh, H.M. et al., "Electron Inversion Layer Mobility in Strained-Si n-MOSFET's with High Channel Doping				
	<u> </u>	Concentration Achieved by Ion Implantation*, DRC Conf. Digest, 2002, pp. 43-44.				
AU		Bae, G.J. et al., "A Novel SiGe-Inserted SOI Structure for High Performance PDSOI CMOSFET", IEDM Tech.				
		Digest, 2000, pp. 667-670.				
AV		Cheng, Z. et al., "SiGe-on-Insulator (SGOI): Substrate Preparation and MOSFET Fabrication for Electron Mobil				
		Evaluation* and conference outline, MIT Microsystem Conf., 10/01, pp. 13-14, 3-pg. outline.	ms, Tech. Labs, Cambridge, MA	, 2001 IEEE Internati. S		
AW		Huang, L.J. et al., "Carrier Mobility Enhancement in Stra	ained Si-on-Insulator Fabricated b	by Wafer Bonding", 2001		
		Sympos. on VLSI Tech. Digest of Technical Papers, pp. 57-58.				
		<u> </u>				

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

DATE CONSIDERED

EXAMINER

Form PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		PRIORITY SERIAL NO 10/243,180		
	LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)	APPLICANT Arup Bhattacharyya			
		PRIORITY FILING DATE September 12, 2002	PRIORITY GROUP 2818		
	OTHER REFERENCES (including Author, Title,	Date, Pertinent Pages, Etc.)			
AX	Mizuno, T. et al., "High Performance CMOS Operation	Mizuno, T. et al., "High Performance CMOS Operation of Strained-SOI MOSFETs Using Thin Film SiGe-on-			
	Insulator Substrate*, 2002 Sympos. on VLSI Tech. Digest of Technical Papers, p. 106-107.				
AY	Tezuka, T. et al., *High-Performance Strained Si-on-In	Tezuka, T. et al., "High-Performance Strained Si-on-Insulator MOSFETs by Novel Fabrication Processes Utilizing			
	Ge-Condensation Technique*, 2002 VLSI Tech. D	Ge-Condensation Technique", 2002 VLSI Tech. Digest of Technical Papers, pp. 96-97.			
AZ	Takagi, S., *Strained-Si- and SiGe-on-Insulator (Straine	Takagi, S., "Strained-Si- and SiGe-on-Insulator (Strained SOI and SGOI) MOSFETs for High Performance/Low			
	Power CMOS Application*, DRC Conf. Digest, 2002, pp. 37-40.				
ВА	"IBM Builds World's Fastest Communications Microchip	"IBM Builds World's Fastest Communications Microchip", Reuters U.S. Company News, 2/25/2002, reprinted from			
	http://activequote300.fidelity.com/rtrnews/_individual	http://activequote300.fidelity.com/rtrnews/_individual_n/1 pg.			
ВВ	Markoff, J., *I.B.M. Circuits are Now Faster and Reduc	Markoff, J., "I.B.M. Circuits are Now Faster and Reduce Use of Power", The New York Times, Feb. 25, 2002,			
	reprinted 3/20/02 from http://story.news.yahoo.com/ news?tmpl=story&u=/nyt/20020225/, 1 pg.				
ВС	Park, J.S. et al., "Normal Incident SiGe/Si Multiple Quantum Well Infrared Detector", IEDM Tech. Digest, 1991,				
	pp. 749-752.				
BD	Current, M.I. et al., "Atomic-Layer Cleaving with Si _x Ge _y Strain Layers for Fabrication of Si and Ge-Rich SOI Device				
	Layers", 2001 IEEE Internati. SOI Conf. 10/01, pp. 11-12.				
BE	Bhattacharyya, A., "The Role of Microelectronic Integration in Environmental Control: A Perspective", Mat. Res.				
	Soc. Symp. Proc. Vol. 344, 1994, pp. 281-293.				
BF	Myers, S.M. et al., "Deuterium Interactions in Oxygen-Implanted Copper", J. Appl. Phys., Vol. 65(1), Jan. 1, 1989,				
	р. 311-321.				
ВG	Saggio, M. et al., "Innovative Localized Lifetime Control in High-Speed IGBT's", IEEE Elec. Dev. Lett., V. 18,				
	No. 7, July 1997, pp. 333-335.				
вн	Lu, N.C.C. et al., "A Buried-Trench DRAM Cell Using a Self-Aligned Epitaxy Over Trench Technology", IEDM				
	Tech. Digest, 1988, pp. 588-591.	Tech. Digest, 1988, pp. 588-591.			
ВІ	Yamada, T. et al., "Spread Source/Drain (SSD) MOSF	Yamada, T. et al., "Spread Source/Drain (SSD) MOSFET Using Selective Silicon Growth for 64Mbit DRAMs",			
	IEDM Tech. Digest, 1989, pp. 35-38.	IEDM Tech. Digest, 1989, pp. 35-38.			
EXAMINER	DATE CONSI	DERED			
EXAMINER: Init	ial if reference considered, whether or not citation is in conform	ance with MPEP 609; Draw line	through citation if not in		

Form PTO-1449	U.S. DEPARTMENT OF C PATENT AND TRADEMAI		ATTY. DOCKET NO. MI22-2362	PRIORITY SERIAL NO 10/243,180		
	LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)		APPLICANT Arup Bhattacharyya			
			PRIORITY FILING DATE September 12, 2002	PRIORITY GROUP 2818		
	OTHER REFERENCES (including Aut	thor, Title, Date	, Pertinent Pages, Etc.)			
ВЈ	BJ van Meer, H. et al., "Ultra-Thin Film Fully-Depleted SOI CMOS with Raised G/S/D Device Architecture					
	nm Applications*, 2001 IEEE Internati. SOI C	nm Applications", 2001 IEEE Internati. SOI Conf. 10/01, pp. 45-46.				
ВК						
BL						
ВМ						
BN						
во						
			= ·			
ВР						
во						
BR						
BS						
ВТ						
EXAMINER	DAT	TE CONSIDE	ERED			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.						